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## Introduction

This one-day seminar sponsored by Semiconductor Equipment and Materials International (SEMI) and SPIE (The International Society for Optical Engineering) provided detailed information on emerging trends and future directions in tools, materials, and quality control for the microlithography industry.

Attendees at the technology seminar learned competitive and new manufacturing techniques in microlithography from internationally recognized experts. The information presented provided data on implementing new-generation process technology and on lowering manufacturing costs through higher yields.

The material contained in this volume provides attendees with a written reference of the information presented during the oral lectures and is also a valuable standalone reference for those not able to attend the live sessions.